

A

Heatsinks for PGA

B

C

D

E

F

G

H

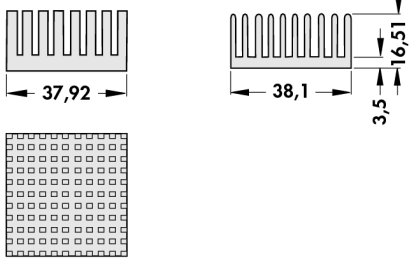
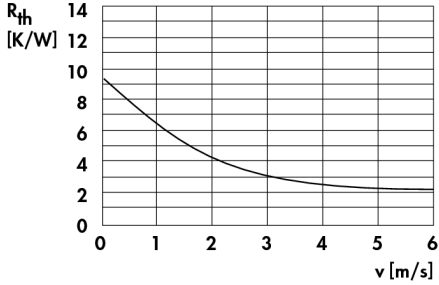
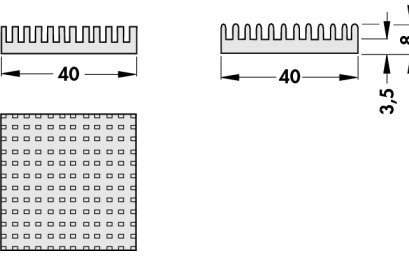
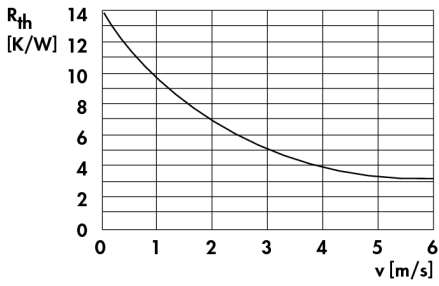
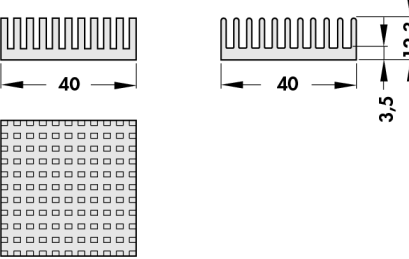
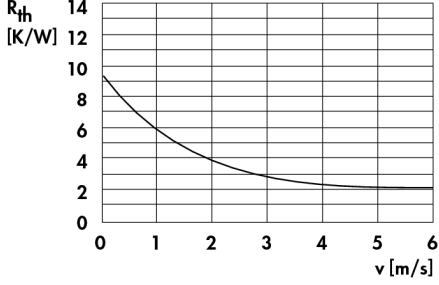
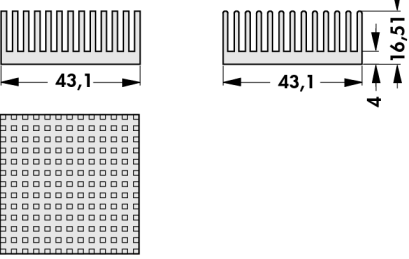
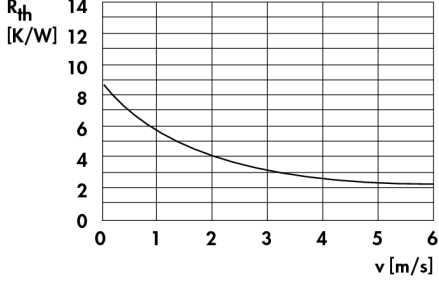
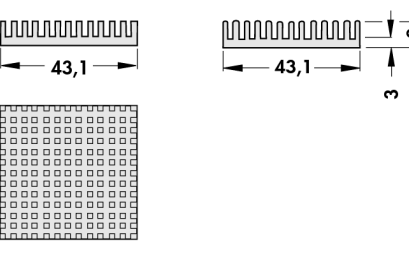
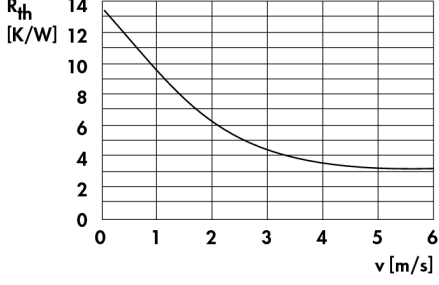
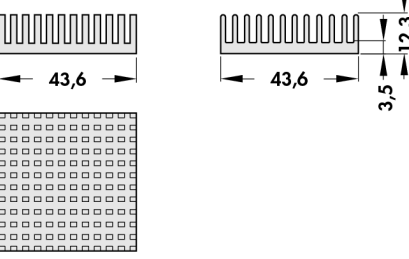
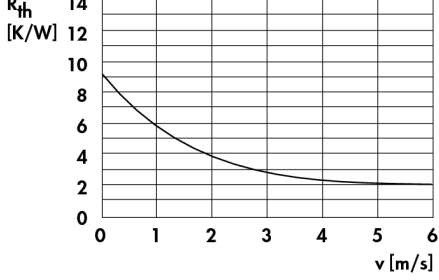
I

K

L

M

N

art. no. ICK PGA 15 x 15 WLF ... 37 x 38		
art. no. ICK PGA 16 x 16 x 8 WLF ... 40 x 40		
art. no. ICK PGA 16 x 16 x 12 WLF ... 40 x 40		
art. no. ICK PGA 17 x 17 WLF ... 43 x 43		
art. no. ICK PGA 17 x 17 x 8 WLF ... 43 x 43		
art. no. ICK PGA 17 x 17 x 12 WLF ... 43 x 43		

B 9

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 14
 Thermal conductive paste → E 12
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27
 Mounting material for semiconduct. → E 34 - 38
 Hole pattern → A 21
 Technical introduction → A 2 - 7